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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep64mc204t-i-tl

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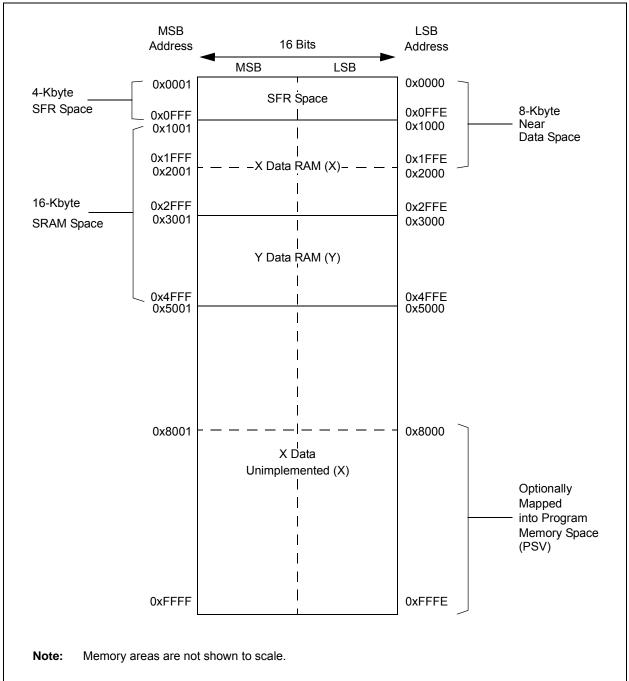


FIGURE 4-9: DATA MEMORY MAP FOR dsPIC33EP128MC20X/50X AND dsPIC33EP128GP50X DEVICES

TABLE 4-37: PMD REGISTER MAP FOR PIC24EPXXXGP20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	_	_	_	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	_	_	AD1MD	0000
PMD2	0762	_	_	_	_	IC4MD	IC3MD	IC2MD	IC1MD	_		_	_	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764		_	_	—	_	CMPMD	_	-	CRCMD	_				_	I2C2MD	_	0000
PMD4	0766		_	_	—	_		_	-	—	_			REFOMD	CTMUMD	_	_	0000
PMD6	076A		—		—	_		_		—	_				—	—		0000
													DMA0MD					
PMD7	076C	_			_								DMA1MD	PTGMD	_			0000
	0700	_	_	_	_	_	_	_	_	_	_	_	DMA2MD	FIGMD	_	_	_	0000
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-38: PMD REGISTER MAP FOR PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	QEI1MD	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	_	_	AD1MD	0000
PMD2	0762	_	_	_	_	IC4MD	IC3MD	IC2MD	IC1MD		_	_	_	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	_	_	_	_	_	CMPMD	_	_	CRCMD	_	_	_	_	_	I2C2MD	_	0000
PMD4	0766	_	_	_	_	_	_	_	_		_	_	_	REFOMD	CTMUMD	_	_	0000
PMD6	076A	_	-	_			PWM3MD	PWM2MD	PWM1MD	_	—	—	_		—	_		0000
													DMA0MD					
PMD7	076C												DMA1MD	PTGMD				0000
FIVID7	0700	_	_	_	_	_	_	_	_	_	_	_	DMA2MD	FIGND	_	_	_	0000
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

5.0 FLASH PROGRAM MEMORY

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXGP/MC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Flash Programming" (DS70609) in the "dsPIC33/PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows for a dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/ MC20X device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear (MCLR). This allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (Table Read) and TBLWT (Table Write) instructions. With RTSP, the user application can write program memory data a single program memory word, and erase program memory in blocks or 'pages' of 1024 instructions (3072 bytes) at a time.

5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the Table Read and Table Write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register, specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS

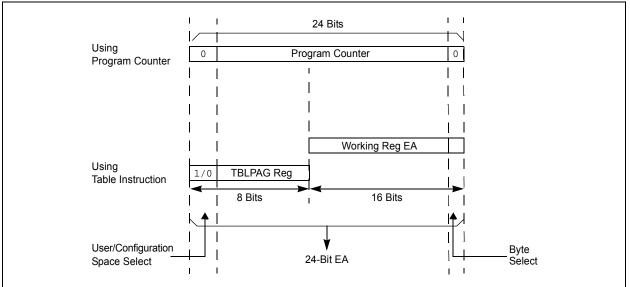
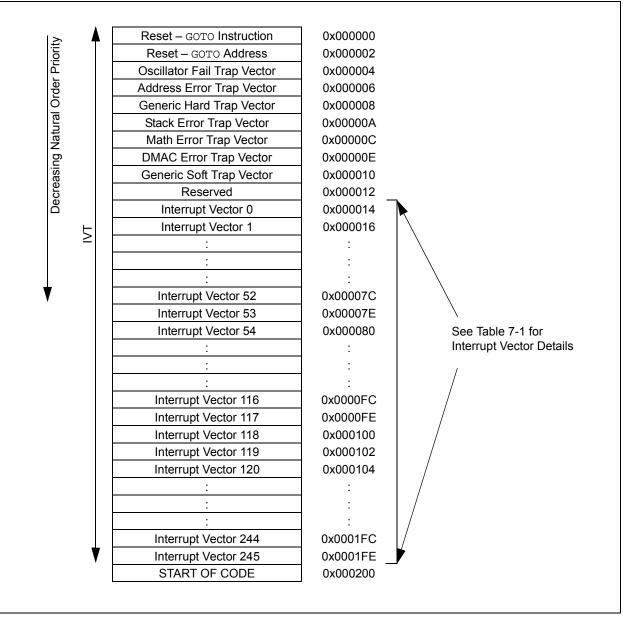


FIGURE 7-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X INTERRUPT VECTOR TABLE



dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

R/S-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0			
FORCE ⁽¹⁾		_	_	—		_				
bit 15							bit 8			
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
IRQSEL7	IRQSEL6	IRQSEL5	IRQSEL4	IRQSEL3	IRQSEL2	IRQSEL1	IRQSEL0 bit			
bit 7										
Legend:		S = Settable b	oit							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	d as '0'				
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown			
bit 15	FORCE: Force	e DMA Transfe	er bit ⁽¹⁾							
	1 = Forces a single DMA transfer (Manual mode)									
	0 = Automatic DMA transfer initiation by DMA request									
bit 14-8	Unimplemen	ted: Read as 'd)'							
bit 7-0	IRQSEL<7:0>	-: DMA Periphe	eral IRQ Num	ber Select bits						
		ECAN1 – TX D		2)						
		IC4 – Input Ca								
		IC3 – Input Ca								
		ECAN1 – RX D SPI2 Transfer I	-							
		UART2TX – UA		itter						
		UART2RX – U								
		TMR5 – Timer5								
	00011011 =	TMR4 – Timer4	1							
		OC4 – Output (
		OC3 – Output (
		ADC1 – ADC1								
		UART1TX – UA								
	00001011 = UART1RX – UART1 Receiver 00001010 = SPI1 – Transfer Done									
	00001000 = TMR3 - Timer3									
		TMR2 – Timer2								
		OC2 – Output (
	00000101 = IC2 – Input Capture 2									
	00000010 =	OC1 – Output (Compare 1							
		IC1 – Input Ca								
	00000000 =	INT0 – Externa	I Interrupt 0							

REGISTER 8-2: DMAXREQ: DMA CHANNEL x IRQ SELECT REGISTER

- **Note 1:** The FORCE bit cannot be cleared by user software. The FORCE bit is cleared by hardware when the forced DMA transfer is complete or the channel is disabled (CHEN = 0).
 - 2: This selection is available in dsPIC33EPXXXGP/MC50X devices only.

REGISTER 8-7: DMAXPAD: DMA CHANNEL X PERIPHERAL ADDRESS REGISTER⁽¹⁾

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PAD	<15:8>			
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PAE)<7:0>			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimplen	nented bit, read	d as '0'	
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown						nown	

bit 15-0 PAD<15:0>: Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-8: DMAXCNT: DMA CHANNEL X TRANSFER COUNT REGISTER⁽¹⁾

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—				CNT<	13:8> (2)		
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CNT<	<7:0> (2)			
bit 7							bit 0
Legend:							
R = Readable b	oit	W = Writable b	bit	U = Unimplen	nented bit, rea	id as '0'	
-n = Value at P	-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown						nown

bit 15-14 Unimplemented: Read as '0'

bit 13-0 CNT<13:0>: DMA Transfer Count Register bits⁽²⁾

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: The number of DMA transfers = CNT<13:0> + 1.

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Notes
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	1, 2
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	1
Low-Power RC Oscillator (LPRC)	Internal	xx	101	1
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	
Primary Oscillator (EC) with PLL (ECPLL)	Primary	0.0	011	1
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	1
Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)	Internal	xx	001	1
Fast RC Oscillator (FRC)	Internal	xx	000	1

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

9.2 Oscillator Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your brouger.
	this URL in your browser: http://www.microchip.com/wwwproducts/ Devices.aspx?dDocName=en555464

9.2.1 KEY RESOURCES

- "Oscillator" (DS70580) in the "dsPIC33/PIC24 Family Reference Manual"
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- · Development Tools

10.0 POWER-SAVING FEATURES

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Watchdog Timer and Power-Saving Modes" (DS70615) in the "dsPIC33/ PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- · Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

PWRSAV	#SLEEP_MODE	;	Put	the	device	into	Sleep mode	
PWRSAV	#IDLE_MODE	;	Put	the	device	into	Idle mode	

10.1 Clock Frequency and Clock Switching

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or highprecision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	
	_	_	_	_	_	_	_	
bit 15							bit	
U-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	
_	-	_	DMA0MD ⁽¹⁾ DMA1MD ⁽¹⁾ DMA2MD ⁽¹⁾ DMA3MD ⁽¹⁾	PTGMD	_	_	_	
bit 7							bit	
Legend: R = Readab -n = Value a		W = Writable '1' = Bit is set		U = Unimplen '0' = Bit is clea	nented bit, read ared	l as '0' x = Bit is unkn	iown	
bit 15-5 bit 4	DMA0MD: DM 1 = DMA0 mo 0 = DMA0 mo DMA1MD: DM 1 = DMA1 mo 0 = DMA1 mo DMA2MD: DM 1 = DMA2 mo 0 = DMA2 mo DMA3MD: DM 1 = DMA3 mo 0 = DMA3 mo	ted: Read as ' MA0 Module Di odule is disable odule is enable MA1 Module Di odule is disable MA2 Module Di odule is disable odule is enable MA3 Module Di odule is disable odule is disable	sable bit ⁽¹⁾ d sable bit ⁽¹⁾ d sable bit ⁽¹⁾ d sable bit ⁽¹⁾ d					
bit 3	PTGMD: PTG Module Disable bit 1 = PTG module is disabled 0 = PTG module is enabled							
bit 2-0	Unimplement	ted: Read as '	0'					
Note 1: T	his single bit ena	ables and disal	oles all four DM	A channels.				

REGISTER 10-6: PMD7: PERIPHERAL MODULE DISABLE CONTROL REGISTER 7

17.0 QUADRATURE ENCODER INTERFACE (QEI) MODULE (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Quadrature Encoder Interface (QEI)" (DS70601) in the "dsPIC33/PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

This chapter describes the Quadrature Encoder Interface (QEI) module and associated operational modes. The QEI module provides the interface to incremental encoders for obtaining mechanical position data.

The operational features of the QEI module include:

- 32-Bit Position Counter
- 32-Bit Index Pulse Counter
- 32-Bit Interval Timer
- 16-Bit Velocity Counter
- 32-Bit Position Initialization/Capture/Compare High register
- 32-Bit Position Compare Low register
- x4 Quadrature Count mode
- External Up/Down Count mode
- External Gated Count mode
- External Gated Timer mode
- Internal Timer mode

Figure 17-1 illustrates the QEI block diagram.

REGISTER 17-2: QEI1IOC: QEI1 I/O CONTROL REGISTER (CONTINUED)

- bit 2 INDEX: Status of INDXx Input Pin After Polarity Control
 - 1 = Pin is at logic '1'
 - 0 = Pin is at logic '0'
- bit 1 QEB: Status of QEBx Input Pin After Polarity Control And SWPAB Pin Swapping 1 = Pin is at logic '1' 0 = Pin is at logic '0'
- bit 0 **QEA:** Status of QEAx Input Pin After Polarity Control And SWPAB Pin Swapping 1 = Pin is at logic '1'
 - 0 = Pin is at logic '0'

20.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "UART" (DS70582) in the "dsPIC33/ PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X family of devices contains two UART modules.

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X device family. The UART is a full-duplex, asynchronous system that can communicate with peripheral devices, such as personal computers, LIN/J2602, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the UxCTS and UxRTS pins, and also includes an IrDA[®] encoder and decoder.

Note: <u>Hardware</u> flow control using UxRTS and UxCTS is not available on all pin count devices. See the "**Pin Diagrams**" section for availability.

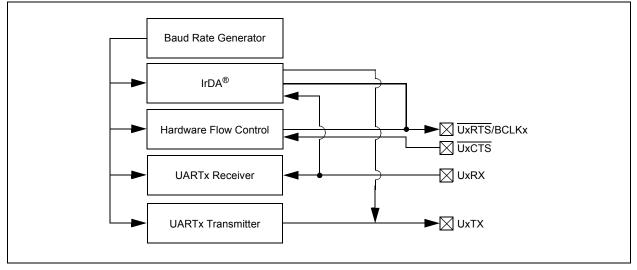
The primary features of the UARTx module are:

- Full-Duplex, 8 or 9-Bit Data Transmission through the UxTX and UxRX Pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop bits
- Hardware Flow Control Option with UxCTS and UxRTS Pins
- Fully Integrated Baud Rate Generator with 16-Bit Prescaler
- Baud Rates Ranging from 4.375 Mbps to 67 bps at 16x mode at 70 MIPS
- Baud Rates Ranging from 17.5 Mbps to 267 bps at 4x mode at 70 MIPS
- 4-Deep First-In First-Out (FIFO) Transmit Data Buffer
- 4-Deep FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for 9-bit mode with Address Detect (9th bit = 1)
- · Transmit and Receive Interrupts
- A Separate Interrupt for all UARTx Error Conditions
- · Loopback mode for Diagnostic Support
- · Support for Sync and Break Characters
- Support for Automatic Baud Rate Detection
- IrDA[®] Encoder and Decoder Logic
- 16x Baud Clock Output for IrDA Support

A simplified block diagram of the UARTx module is shown in Figure 20-1. The UARTx module consists of these key hardware elements:

- · Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 20-1: UARTx SIMPLIFIED BLOCK DIAGRAM



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FIGURE 22-1: CTMU BLOCK DIAGRAM



5: The switch connected to ADC CH0 is closed when IDISSEN (CTMUCON1<9>) = 1, and opened when IDISSEN = 0.

22.1 CTMU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the
	product page using the link above, enter
	this URL in your browser:
	http://www.microchip.com/wwwproducts/
	Devices.aspx?dDocName=en555464

22.1.1 KEY RESOURCES

- "Charge Time Measurement Unit (CTMU)" (DS70661) in the "dsPIC33/PIC24 Family Reference Manual"
- Code Samples
- · Application Notes
- · Software Libraries
- Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- · Development Tools

25.1.2 OP AMP CONFIGURATION B

Figure 25-7 shows a typical inverting amplifier circuit with the output of the op amp (OAxOUT) externally routed to a separate analog input pin (ANy) on the device. This op amp configuration is slightly different in terms of the op amp output and the ADC input connection, therefore, RINT1 is not included in the transfer function. However, this configuration requires the designer to externally route the op amp output (OAxOUT) to another analog input pin (ANy). See Table 30-53 in **Section 30.0 "Electrical Characteristics"** for the typical value of RINT1. Table 30-60 and Table 30-61 in **Section 30.0 "Electrical Characteristics"** describe the minimum sample time (TSAMP) requirements for the ADC module in this configuration.

Figure 25-7 also defines the equation to be used to calculate the expected voltage at point VOAxOUT. This is the typical inverting amplifier equation.

25.2 Op Amp/Comparator Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

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	Devices.aspx?dDocName=en555464

25.2.1 KEY RESOURCES

- "Op Amp/Comparator" (DS70357) in the "dsPIC33/PIC24 Family Reference Manual"
- Code Samples
- · Application Notes
- Software Libraries
- · Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- Development Tools

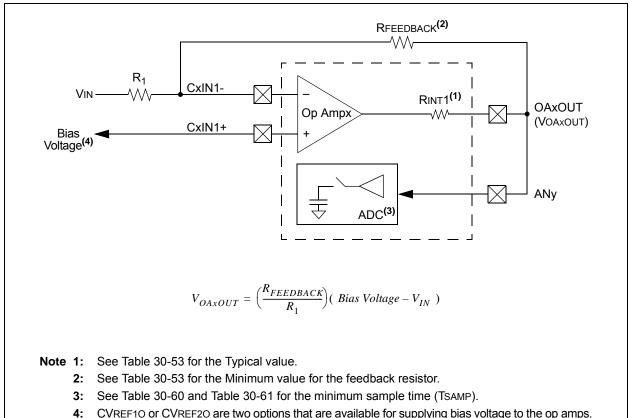


FIGURE 25-7: OP AMP CONFIGURATION B

Base Instr #	Assembly Mnemonic		Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected	
25	DAW	DAW Wn		Wn = decimal adjust Wn	1	1	С	
26	DEC	DEC	f	f = f - 1	1	1	C,DC,N,OV,Z	
		DEC	f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z	
		DEC	Ws,Wd	Wd = Ws - 1	1	1	C,DC,N,OV,Z	
27	DEC2	DEC2	f	f = f - 2	1	1	C,DC,N,OV,Z	
		DEC2	f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z	
		DEC2	Ws,Wd	Wd = Ws - 2	1	1	C,DC,N,OV,Z	
28	DISI	DISI	#lit14	Disable Interrupts for k instruction cycles	1	1	None	
29	DIV	DIV.S	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV	
		DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV	
		DIV.U	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV	
		DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV	
30	DIVF	DIVF	Wm , Wn ⁽¹⁾	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV	
31	DO	DO	#lit15,Expr ⁽¹⁾	Do code to PC + Expr, lit15 + 1 times	2	2	None	
		DO	Wn, Expr(1)	Do code to PC + Expr, (Wn) + 1 times	2	2	None	
32	ED	ED	Wm*Wm,Acc,Wx,Wy,Wxd ⁽¹⁾	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB	
33	EDAC	EDAC	Wm*Wm,Acc,Wx,Wy,Wxd ⁽¹⁾	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB	
34	EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None	
35	FBCL	FBCL	Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	С	
36	FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	С	
37	FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	С	
38	GOTO	GOTO	Expr	Go to address	2	4	None	
		GOTO	Wn	Go to indirect	1	4	None	
		GOTO.L	Wn	Go to indirect (long address)	1	4	None	
39	INC	INC	f	f = f + 1	1	1	C,DC,N,OV,Z	
		INC	f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z	
		INC	Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z	
40	INC2	INC2	f	f = f + 2	1	1	C,DC,N,OV,Z	
		INC2	f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z	
		INC2	Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z	
41	IOR	IOR	f	f = f .IOR. WREG	1	1	N,Z	
		IOR	f,WREG	WREG = f .IOR. WREG	1	1	N,Z	
		IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z	
		IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z	
		IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z	
42	LAC	LAC	Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB	
43	LNK	LNK	#lit14	Link Frame Pointer	1	1	SFA	
44	LSR	LSR	f	f = Logical Right Shift f	1	1	C,N,OV,Z	
		LSR	f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z	
		LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z	
		LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z	
		LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z	
45	MAC	MAC	Wm*Wn, Acc, Wx, Wxd, Wy, Wyd, AWB ⁽¹⁾	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB	
		MAC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd(1)	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB	

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

DC CHARACTERISTICS			$\begin{tabular}{ l l l l l l l l l l l l l l l l l l l$						
Param No.	Symbol	Characteristic	Min.	Тур.	Max.	Units	Conditions		
Operati	ng Voltag	e							
DC10	Vdd	Supply Voltage	3.0		3.6	V			
DC16	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	-	_	Vss	V			
DC17	Svdd	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.03	_	—	V/ms	0V-1V in 100 ms		

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-5: FILTER CAPACITOR (CEFC) SPECIFICATIONS

	Standard Operating Conditions (unless otherwise stated):Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended									
Param No.	Symbol Characteristics Min Typ Max Units Comments									
	Cefc	External Filter Capacitor Value ⁽¹⁾	4.7	10		μF	Capacitor must have a low series resistance (< 1 Ohm)			

Note 1: Typical VCAP voltage = 1.8 volts when VDD \geq VDDMIN.

30.2 AC Characteristics and Timing Parameters

This section defines dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/ MC20X AC characteristics and timing parameters.

TABLE 30-15: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)
AC CHARACTERISTICS	Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended Operating voltage VDD range as described in Section 30.1 "DC
	Characteristics".

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

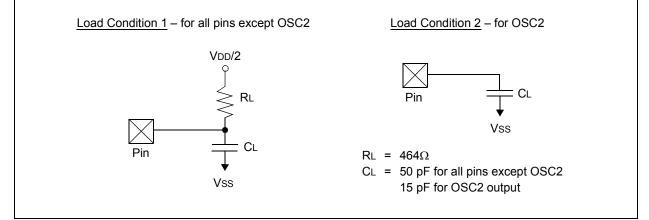


TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min.	Тур.	Max.	Units	Conditions
DO50	Cosco	OSC2 Pin	_	—	15		In XT and HS modes, when external clock is used to drive OSC1
DO56	Сю	All I/O Pins and OSC2	—	_	50	pF	EC mode
DO58	Св	SCLx, SDAx	_	_	400	pF	In I ² C™ mode

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

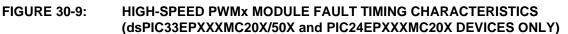


TABLE 30-23: TIME	1 EXTERNAL CLOCK TIMING REQUI	REMENTS ⁽¹⁾
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			$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$					
Param No.	Symbol	Charao	cteristic ⁽²⁾	Min.	Тур.	Max.	Units	Conditions
TA10	ТтхН	T1CK High Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N		_	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	35	_	—	ns	
TA11	ΤτχL	T1CK Low Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N		_	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	10	_	_	ns	
TA15	ΤτχΡ	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 Tcy + 40)/N	_	_	ns	N = prescale value (1, 8, 64, 256)
OS60	Ft1		ange (oscillator etting bit, TCS	DC		50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 Tcy + 40	—	1.75 Tcy + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized, but are not tested in manufacturing.



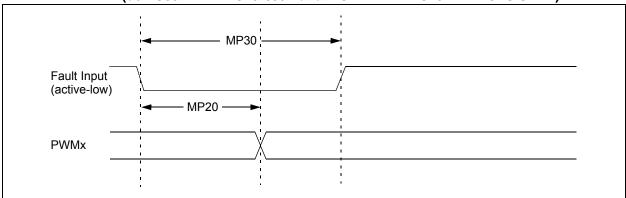


FIGURE 30-10: HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

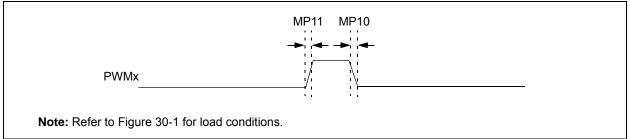


TABLE 30-29: HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			$\begin{tabular}{lllllllllllllllllllllllllllllllllll$				
Param No.	Symbol	Characteristic ⁽¹⁾	Min.	Тур.	Max.	Units	Conditions
MP10	TFPWM	PWMx Output Fall Time		—	_	ns	See Parameter DO32
MP11	TRPWM	PWMx Output Rise Time	_	—	_	ns	See Parameter DO31
MP20	Tfd	Fault Input ↓ to PWMx I/O Change	_	_	15	ns	
MP30	Tfh	Fault Input Pulse Width	15	—	_	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

NOTES: